

**AMENDMENTS TO THE CLAIMS**

Please cancel claims 2, 4, 6-8 and 10-11 without prejudice or disclaimer of their underlying subject matter.

1-5. (Canceled)

5. (Previously presented) An imaging device comprising:

a substrate; and

an imaging element having a light receiving portion on a first side, and a shielding layer on a second side that is opposite the first side,

wherein said imaging element is flip chip mounted on the substrate such that said first side is opposed to the substrate.

6-8. (Canceled)

9. (Previously presented) A camera system using a camera module comprising:

a substrate having a through-hole for light transmission;

an imaging element having a light receiving portion on a first surface of the imaging element and a shielding layer on a back surface of the imaging element,

wherein said imaging element is flip chip mounted on a first side of the substrate such that the light receiving portion is exposed through the through-hole, and a lens unit is mounted on a second side of the substrate.

10-11. (Canceled)

Please add the following new claims.

12. (New) An optical system having an optical module, the optical module comprising:

a substrate, the substrate including a plate of a first material adhered to a wiring board of a material other than the first material, a through-hole extending through the plate and the wiring board;

an optical element mounted to the wiring board, the optical element including a light receiving portion, the wiring board being between the optical element and the plate; and

a lens unit mounted to the plate, the lens unit including a lens, the plate being between the wiring board and the lens unit,

wherein the light receiving portion and the lens are disposed along an optical axis, the optical axis extending through the through-hole.

13. (New) The optical system of claim 12, wherein the lens is mounted to a lens barrel, the lens barrel being moveable in a direction along the optical axis.

14. (New) The optical system of claim 12, wherein the first material is a metal.

15. (New) The optical system of claim 12, wherein the optical element includes a shielding layer, the light receiving portion being between the shielding layer and the lens.

16. (New) The optical system of claim 15, wherein the shielding layer is a metal layer.

17. (New) The optical system of claim 15, wherein the shielding layer is a resin layer.

18. (New) The optical system of claim 17, wherein a portion of the resin layer is in contact with the wiring board.